

## Full Material Declaration for attached parts list

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## Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 January 2007 [Approved on 14 June 2016, 08:22 GMT]

## Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.55000%	Gold	7440-57-5	1.50000%
			Silicon dioxide	14808-60-7	5.05000%
			Silicon	7440-21-3	93.45000%
Die attach	Lead and Lead alloys	0.38000%	Silver	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	EP (Epoxy resin)	41.00000%	Carbon black	1333-86-4	0.50000%
			ALUMINUM(III) HYDROXIDE	21645-51-2	2.80000%
			resin	9003-35-4	8.60000%
			Epoxy resin 89	26335-32-0	18.00000%
			Quartz silica	14808-60-7	70.10000%
Leadfinish	Tin plating	0.47000%	Tin	7440-31-5	100.00000%
Leadframe	Copper alloys	57.60000%	Copper	7440-50-8	100.00000%

## Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
GBIxx	Bridge Rectifier Single Inline	7	g